

MC6802-6808-68B

Microprocessor with Clock and Optional RAM

The MC6802 is a monolithic 8-bit microprocessor that contains all the registers and accumulators of the present MC6800 plus an internal clock oscillator and driver on the same chip. In addition, the MC6802 has 128 bytes of on-board RAM located at hex addresses \$0000 to \$007F. The first 32 bytes of RAM, at hex addresses \$0000 to \$001F, may be retained in a low power mode by utilizing V_{CC} standby; thus, facilitating memory retention during a power-down situation.

The MC6802 is completely software compatible with the MC6800 as well as the entire M6800 family of parts. Hence, the MC6802 is expandable to 64K words.

The MC6802NS is identical to the MC6802 without standby RAM feature. The MC6808 is identical to the MC6802 without on-board RAM.

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer (OCM).

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

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The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FOR REFERENCE ONLY

3501 ED BLUESTEIN BLVD., AUSTIN, TEXAS 78721

MC6802 MC6808 MC6802NS

MICROPROCESSOR WITH CLOCK AND OPTIONAL RAM

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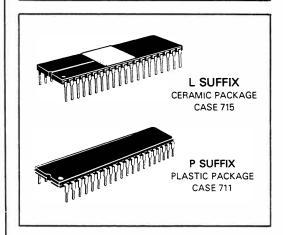
The MC6802NS is identical to the MC6802 without standby RAM feature. The MC6808 is identical to the MC6802 without on-board RAM.

- On-Chip Clock Circuit
- 128×8 Bit On-Chip RAM
- 32 Bytes of RAM are Retainable
- Software-Compatible with the MC6800
- Expandable to 64K Words
- Standard TTL-Compatible Inputs and Outputs
- 8-Bit Word Size
- 16-Bit Memory Addressing
- Interrupt Capability

MOS

(N-CHANNEL, SILICON-GATE, DEPLETION LOAD)

MICROPROCESSOR WITH CLOCK AND OPTIONAL RAM

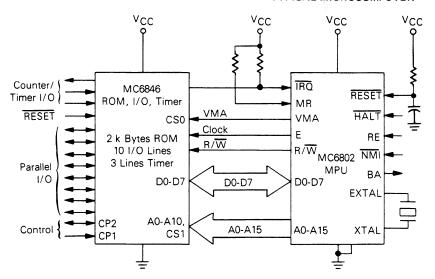


ORDERING INFORMATION

Package Type	Frequency (MHz)	Temperature	Order Number
Ceramic	1.0	0°C to 70°C	MC6802L
L Suffix	1.0	-40°C to 85°C	MC6802CL
	1.0	0°C to 70°C	MC6802NSL
	1.0	0°C to 70°C	MC6808L
	1.5	0°C to 70°C	MC68A02L
	1.5	-40°C to 85°C	MC68A02CL
	1.5	0°C to 70°C	MC68A08L
	2.0	0°C to 70°C	MC68B02L
	2.0	0°C to 70°C	MC68B08L
Plastic	1.0	0°C to 70°C	MC6802P
P Suffix	1.0	-40°C to 85°C	MC6802CP
	1.0	0°C to 70°C	MC6802NSP
	1.0	0°C to 70°C	MC6808P
	1.5	0°C to 70°C	MC68A02P
	1.5	-40°C to 85°C	MC68A02CP
	1.5	0°C to 70°C	MC68A08P
	2.0	0°C to 70°C	MC68B02P
	2.0	0°C to 70°C	MC68B08P

PIN ASSIGNMENT VSS 1 40 D RESET HALT 2 39 DEXTAL 38 TXTAL MR 13 37 T E IRQ 4 36 TRE** VMA 15 <u>NMI</u> **1**6 35 VCC Standby* 34 7 R/W BAD 7 33 DO VCC 48 A0 🛛 9 32 DD1 31 D2 A1 10 30 D3 A2 11 A3 112 29 D D4 28 🛮 D5 A4 113 A5 114 27 D6 26 D7 A6 115 25 D A 15 A7 🛮 16 A8 117 24 🛮 A14 A9 118 23 A13 A10 🛛 19 22 A12 21 D VSS *Pin 35 must be tied to 5 V on the MC6802NS

TYPICAL MICROCOMPUTER



This block diagram shows a typical cost effective microcomputer. The MPU is the center of the microcomputer system and is shown in a minimum system interfacing with a ROM combination chip. It is not intended that this system be limited to this function but that it be expandable with other parts in the M6800 Microcomputer family.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	Vcc	-0.3 to $+7.0$	V
Input Voltage	V _{in}	-0.3 to $+7.0$	V
Operating Temperature Range MC6802, MC680A02, MC680B02 MC6802C, MC680A02C MC6802NS MC6808, MC68A08, MC68B08	ТД	0 to +70 -40 to +85 0 to +70 0 to +70	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

This input contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this highimpedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., either VSS or VCC).

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Average Thermal Resistance (Junction to Ambient)			
Plastic	۵.,	100	°C/W
Ceramic	$\theta_{ m JA}$	50	C/VV

POWER CONSIDERATIONS

The average chip-junction temperature, T_J, in °C can be obtained from:

$$T_{J} = T_{A} + (P_{D} \bullet \theta_{JA})$$

$$(1)$$

Where:

T_A = Ambient Temperature, °C

 $\theta_{JA} = Package Thermal Resistance, Junction-to-Ambient, °C/W$

PD = PINT + PPORT

PINT≡ICC×VCC, Watts - Chip Internal Power

PPORT = Port Power Dissipation, Watts - User Determined

drive Darlington bases or sink LED loads.

An approximate relationship between PD and TJ (if PPORT is neglected) is:

$$P_D = K \div (T_J + 273 \,^{\circ}C)$$
 (2)

Solving equations 1 and 2 for K gives:

$$K = P_{D} \bullet (T_{A} + 273 \circ C) + \theta_{JA} \bullet P_{D}^{2}$$

Where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring PD (at equilibrium) for a known TA. Using this value of K the values of PD and TJ can be obtained by solving equations (1) and (2) iteratively for any value of TA.



DC ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 Vdc ±5%, V_{SS} = 0, T_A = 0 to 70°C, unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
Input High Voltage	Logic, EXTAL RESET	ViH	V _{SS} +2.0 V _{SS} +4.0	-	Vcc Vcc	V
Input Low Voltage	Logic, EXTAL, RESET	VIL	V _{SS} -0.3	_	$V_{SS} + 0.8$	V
Input Leakage Current (V _{in} = 0 to 5.25 V, V _{CC} = max)	Logic	lin	_	1.0	2.5	μΑ
Output High Voltage $ \begin{aligned} &(I_{LOad} = -205\mu\text{A},V_{CC} = \text{min}) \\ &(I_{LOad} = -145\mu\text{A},V_{CC} = \text{min}) \\ &(I_{LOad} = -100\mu\text{A},V_{CC} = \text{min}) \end{aligned} $	D0-D7 A0-A15, R/ W , VMA, E BA	Vон	V _{SS} +2.4 V _{SS} +2.4 V _{SS} +2.4	- - -	- - -	V
Output Low Voltage (I _{Load} = 1.6 mA, V _{CC} = min)	· · · · · · · · · · · · · · · · · · ·	VOL	_	_	V _{SS} + 0.4	V
Internal Power Dissipation (Measured at T _A = 0°C)		PINT	_	0.750	1.0	W
V _{CC} Standby	Power Down Power Up	V _{SBB} V _{SB}	4.0 4.75	_ _	5.25 5.25	٧.
Standby Current		ISBB	_	-	8.0	mΑ
Capacitance # $(V_{in} = 0, T_A = 25$ °C, f = 1.0 MHz)	D0-D7 Logic Inputs, EXTAL	C _{in}	_	10 6.5	12.5 10	pF
	A0-A15, R/\overline{W} , VMA	Cout	_	_	12	pF

^{*}In power-down mode, maximum power dissipation is less than 42 mW.

$\textbf{CONTROL TIMING} \ (\text{V}_{CC} = 5.0 \ \text{V} \ \pm 5\%, \ \text{V}_{SS} = \text{0}, \ \text{T}_{A} = \text{T}_{L} \ \text{to T}_{H}, \ \text{unless otherwise noted})$

Characteristics	Symbol	MC68 MC68	02NS		8A02 8A08		8B02 8B08	Unit	
		Min	Max	Min	Max	Min	Max		
Frequency of Operation	fo	0.1	1.0	0.1	1.5	0.1	2.0	MHz	
Crystal Frequency	fXTAL	1.0	4.0	1.0	6.0	1.0	8.0	MHz	
External Oscillator Frequency	4xf _O	0.4	4.0	0.4	6.0	0.4	8.0	MHz	
Crystal Oscillator Start Up Time	t _{rc}	100	-	100	-	100	-	ms	
Processor Controls (HALT, MR, RE, RESET, IRQ NMI) Processor Control Setup Time Processor Control Rise and Fall Time (Does Not Apply to RESET)	tPCS tPCr, tPCf	200 –	- 100	140 –	- 100	110	- 100	ns ns	



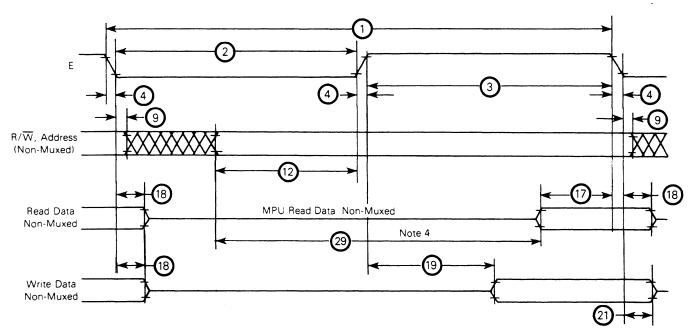
[#]Capacitances are periodically sampled rather than 100% tested.

BUS TIMING CHARACTERISTICS

ldent. Number	Characteristic	Symbol		5802 302NS 6808		8A02 8A08	MC6	Unit	
			Min	Max	Min	Max	Min	Max	
1	Cycle Time	tcyc	1.0	10	0.667	10	0.5	10	μS
2	Pulse Width, E Low	PWEL	450	5000	280	5000	210	5000	ns
3	Pulse Width, E High	PWEH	450	9500	280	9700	220	9700	ns
4	Clock Rise and Fall Time	t _r , t _f	_	25	_	25	-	25	ns
9	Address Hold Time*	^t AH	20	-	20	-	20	_	ns
12	Non-Muxed Address Valid Time to E (See Note 5)	tAV1 tAV2	160 -	- 270	100	-	50 -	_	ns
17	Read Data Setup Time	†DSR	100	_	70	_	60	_	ns
18	Read Data Hold Time	^t DHR	10	_	10	_	10	_	ns
19	Write Data Delay Time	tDDW	_	225	-	170	_	160	ns
21	Write Data Hold Time*	tDHW	30	-	20	_	20	-	ns
29	Usable Access Time (See Note 4)	tACC	535	-	335	-	235	_	ns

^{*} Address and data hold times are periodically tested rather than 100% tested.

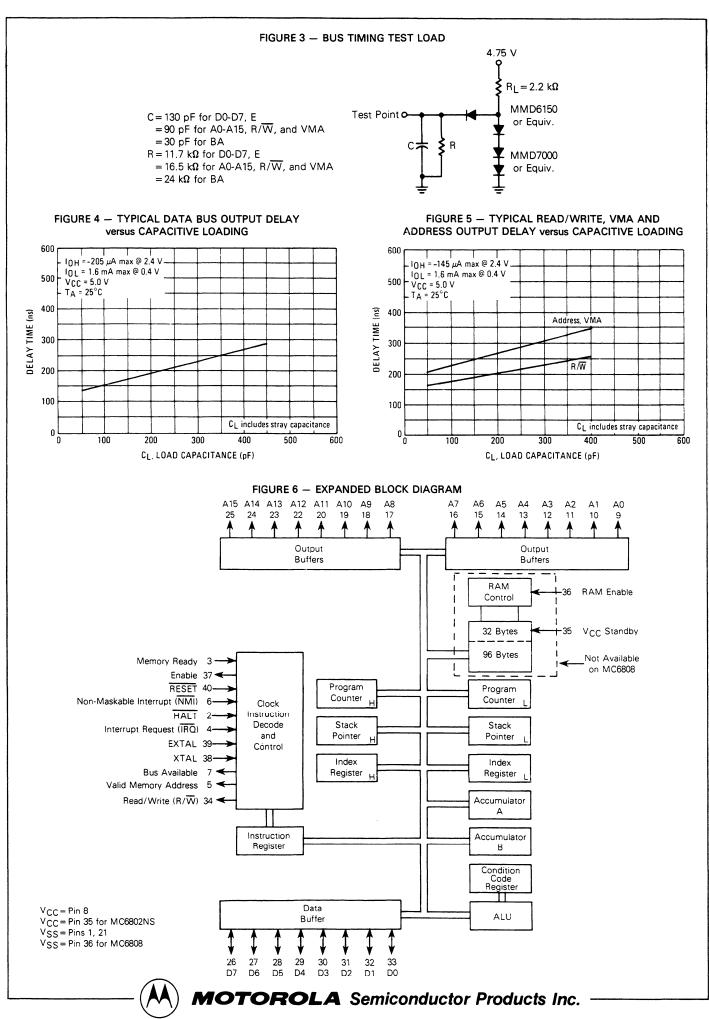
FIGURE 2 - BUS TIMING



NOTES:

- 1. Voltage levels shown are V_L≤0.4 V, V_H≥2.4 V, unless otherwise specified.
- 2. Measurement points shown are 0.8 V and 2.0 V, unless otherwise noted.
- 3. All electricals shown for the MC6802 apply to the MC6802NS and MC6808, unless otherwise noted.
- 4. Usable access time is computed by: 12+3+4-17.
- 5. If programs are not executed from on-board RAM, TAV1 applies. If programs are to be stored and executed from on-board RAM, TAV2 applies. For normal data storage in the on-board RAM, this extended delay does not apply. Programs cannot be executed from on-board RAM when using A and B parts (MC68A02, MC68B08, MC68B08). On-board RAM can be used for data storage with all parts.
- 6. All electrical and control characteristics are referenced from: $T_L = 0$ °C minimum and $T_H = 70$ °C maximum.





MPU REGISTERS

A general block diagram of the MC6802 is shown in Figure 6. As shown, the number and configuration of the registers are the same as for the MC6800. The 128 × 8-bit RAM* has been added to the basic MPU. The first 32 bytes can be retained during power-up and power-down conditions via the RE signal.

The MC6802NS is identical to the MC6802 except for the standby feature on the first 32 bytes of RAM. The standby feature does not exist on the MC6802NS and thus pin 35 must be tied to 5 V.

The MC6808 is identical to the MC6802 except for onboard RAM. Since the MC6808 does not have on-board RAM pin 36 must be tied to ground allowing the processor to utilize up to 64K bytes of external memory.

The MPU has three 16-bit registers and three 8-bit registers available for use by the programmer (Figure 7).

PROGRAM COUNTER

The program counter is a two byte (16-bit) register that points to the current program address.

STACK POINTER

The stack pointer is a two byte register that contains the address of the next available location in an external push-down/pop-up stack. This stack is normally a random access

read/write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be non-volatile.

INDEX REGISTER

The index register is a two byte register that is used to store data or a 16-bit memory address for the indexed mode of memory addressing.

ACCUMULATORS

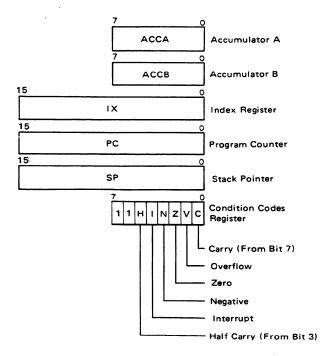
The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit (ALU).

CONDITION CODE REGISTER

The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative (N), Zero (Z), Overflow (V), Carry from bit 7 (C), and Half Carry from bit 3 (H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit (I). The unused bits of the Condition Code Register (b6 and b7) are ones.

Figure 8 shows the order of saving the microprocessor status within the stack.

FIGURE 7 — PROGRAMMING MODEL OF THE MICROPROCESSING UNIT





^{*}If programs are not executed from on-board RAM, TAV1 applies. If programs are to be stored and executed from on-board RAM, TAV2 applies. For normal data storage in the on-board RAM, this extended delay does not apply. Programs cannot be executed from on-board RAM when using A and B parts (MC68A02, MC68A08, MC68B02, and MC68B08). On-board RAM can be used for data storage with all parts.

FIGURE 8 — SAVING THE STATUS OF THE MICROPROCESSOR IN THE STACK

SP = Stack Pointer

CC = Condition Codes (Also called the Processor Status Byte)

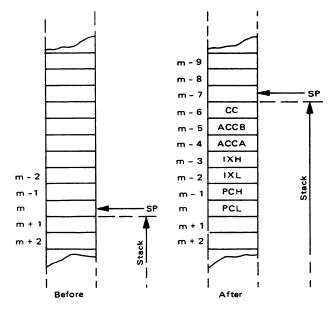
ACCB = Accumulator B

ACCA = Accumulator A

IXH = Index Register, Higher Order 8 Bits IXL = Index Register, Lower Order 8 Bits

PCH = Program Counter, Higher Order 8 Bits

PCL = Program Counter, Lower Order 8 Bits



MPU SIGNAL DESCRIPTION

Proper operation of the MPU requires that certain control and timing signals be provided to accomplish specific functions and that other signal lines be monitored to determine the state of the processor. These control and timing signals are similar to those of the MC6800 except that TSC, DBE, ϕ 1, ϕ 2 input, and two unused pins have been eliminated, and the following signal and timing lines have been added:

RAM Enable (RE)

Crystal Connections EXTAL and XTAL

Memory Ready (MR)

VCC Standby

Enable ϕ 2 Output (E)

The following is a summary of the MPU signals:

ADDRESS BUS (A0-A15)

Sixteen pins are used for the address bus. The outputs are capable of driving one standard TTL load and 90 pF. These lines do not have three-state capability.

DATA BUS (D0-D7)

Eight pins are used for the data bus. It is bidirectional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130 pF.

Data bus will be in the output mode when the internal RAM is accessed and RE will be high. This prohibits external data entering the MPU. It should be noted that the internal RAM is fully decoded from \$0000 to \$007F. External RAM at \$0000 to \$007F must be disabled when internal RAM is accessed.

HALT

When this input is in the low state, all activity in the machine will be halted. This input is level sensitive. In the HALT mode, the machine will stop at the end of an instruction, bus available will be at a high state, valid memory address will be at a low state. The address bus will display the address of the next instruction.

To ensure single instruction operation, transition of the HALT line must occur tpcs before the falling edge of E and the HALT line must go high for one clock cycle.

HALT should be tied high if not used. This is good engineering design practice in general and necessary to ensure proper operation of the part.

READ/WRITE (R/W)

This TTL-compatible output signals the peripherals and memory devices whether the MPU is in a read (high) or write (low) state. The normal standby state of this signal is read (high). When the processor is halted, it will be in the read state. This output is capable of driving one standard TTL load and 90 pF.

VALID MEMORY ADDRESS (VMA)

This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90 pF may be directly driven by this active high signal.

BUS AVAILABLE (BA) — The bus available signal will normally be in the low state; when activated, it will go to the high state indicating that the microprocessor has stopped and that the address bus is available (but not in a three-state condition). This will occur if the HALT line is in the low state or the processor is in the WAIT state as a result of the execution of a WAIT instruction. At such time, all three-state output drivers will go to their off-state and other outputs to their normally inactive level. The processor is removed from the



WAIT state by the occurrence of a maskable (mask bit l=0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30 pF.

INTERRUPT REQUEST (IRQ)

A low level on this input requests that an interrupt sequence be generated within the machine. The processor will wait until it completes the current instruction that is being excuted before it recognizes the request. At that time, if the interrupt mask bit in the condition code register is not set, the machine will begin an interrupt sequence. The index register, program counter, accumulators, and condition code register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit vectoring address which is located in memory locations \$FFF8 and \$FFF9 is loaded which causes the MPU to branch to an interrupt routine in memory.

The HALT line must be in the high state for interrupts to be serviced. Interrupts will be latched internally while HALT is low.

A nominal 3 k Ω pullup resistor to VCC should be used for wire-OR and optimum control of interrupts. IRQ may be tied directly to VCC if not used.

RESET

This input is used to reset and start the MPU from a power-down condition, resulting from a power failure or an initial start-up of the processor. When this line is low, the MPU is inactive and the information in the registers will be lost. If a high level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execution of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced high. For the restart, the last two (\$FFFE, \$FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by IRQ. Power-up and reset timing and powerdown sequences are shown in Figures 9 and 10, respectively.

RESET, when brought low, must be held low at least three clock cycles. This allows adequate time to respond internally to the reset. This is independent of the trc power-up reset that is required.

When RESET is released it must go through the low-tohigh threshold without bouncing, oscillating, or otherwise causing an erroneous reset (less than three clock cycles). This may cause improper MPU operation until the next valid reset.

NON-MASKABLE INTERRUPT (NMI)

A low-going edge on this input requests that a nonmaskable interrupt sequence be generated within the processor. As with the interrupt request signal, the processor will complete the current instruction that is being executed before it recognizes the NMI signal. The interrupt mask bit in the condition code register has no effect on NMI.

The index register, program counter, accumulators, and condition code registers are stored away on the stack. At the end of the cycle, a 16-bit vectoring address which is located in memory locations \$FFFC and \$FFFD is loaded causing the MPU to branch to an interrupt service routine in memory.

A nominal 3 $k\Omega$ pullup resistor to VCC should be used for wire-OR and optimum control of interrupts. NMI may be tied

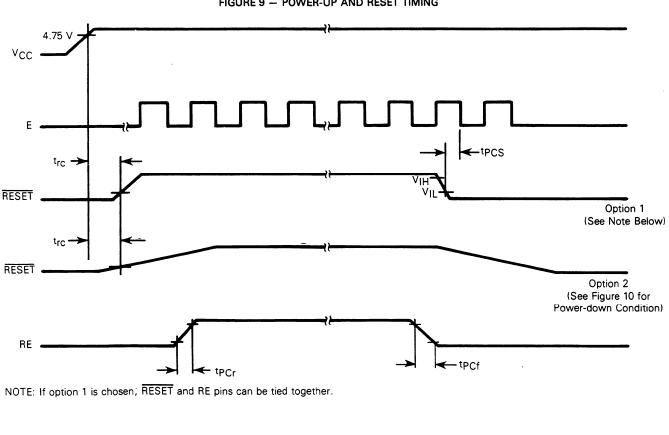


FIGURE 9 - POWER-UP AND RESET TIMING

directly to V_{CC} if not used. Inputs $\overline{\text{IRO}}$ and $\overline{\text{NMI}}$ are hardware interrupt lines that are sampled when E is high and will start the interrupt routine on a low E following the completion of an instruction.

Figure 11 is a flowchart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.

TABLE 1 - MEMORY MAP FOR INTERRUPT VECTORS

Ved	ctor	Description
MS	LS	Description
\$FFFE	\$FFFF	Restart
\$FFFC	\$FFFD	Non-Maskable Interrupt
\$FFFA	\$FFFB	Software Interrupt
\$FFF8	\$FFF9	Interrupt Request

FIGURE 10 — POWER-DOWN SEQUENCE 4.75 V VCC tCPS tPCf → RE

FIGURE 11 - MPU FLOWCHART

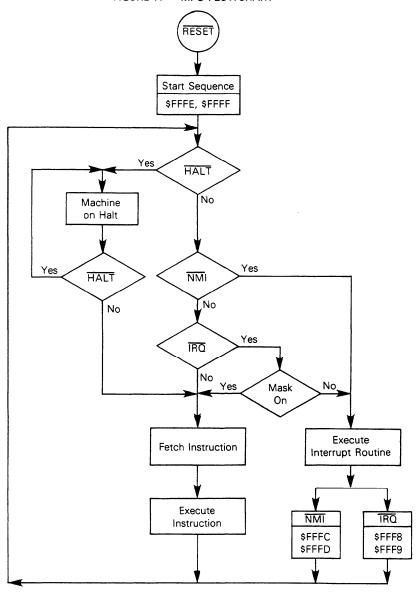
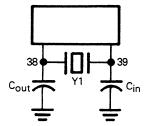


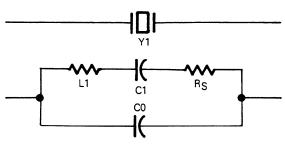


FIGURE 12 — CRYSTAL SPECIFICATIONS



Y1 _	C _{in}	C _{out}
3.58 MHz	27 pF	27 pF
4 MHz	27 pF	27 pF
6 MHz	20 pF	20 pF
8 MHz	18 pF	18 pF

Crystal Loading



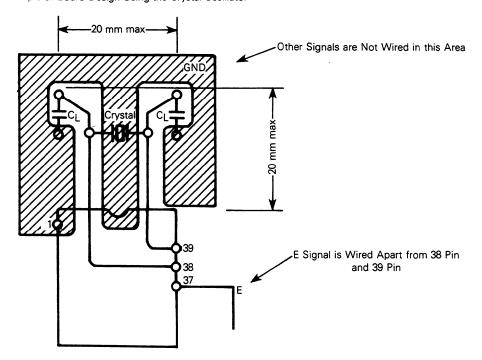
Nominal Crystal Parameters*

	3.58 MHz	4.0 MHz	6.0 MHz	8.0 MHz
RS	60 Ω	50 Ω	30-50 Ω	20-40 Ω
CO	3.5 pF	6.5 pF	4-6 pF	4-6 pF
C1	0.015 pF	0.025 pF	0.01-0.02 pF	0.01-0.02 pF
Q	>40K	>30K	> 20K	> 20K

^{*}These are representative AT-cut parallel resonance crystal parameters only. Crystals of other types of cuts may also be used.

Figure 13 — SUGGESTED PC BOARD LAYOUT

Example of Board Design Using the Crystal Oscillator





MOTOROLA Semiconductor Products Inc.

FIGURE 14 - MEMORY READY SYNCHRONIZATION

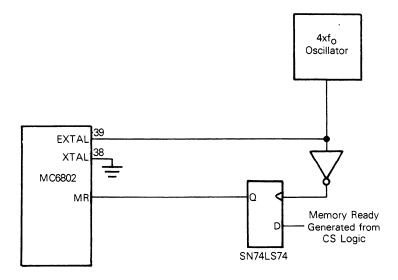
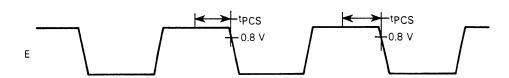


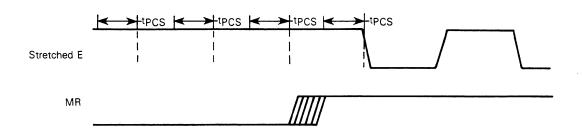
FIGURE 15 - MR NEGATIVE SETUP TIME REQUIREMENT

E Clock Stretch



The E clock will be stretched at end of E high of the cycle during which MR negative meets the tpcs setup time. The tpcs setup time is referenced to the fall of E. If the tpcs setup time is not met, E will be stretched at the end of the next E-high ½ cycle. E will be stretched in integral multiples of ½ cycles.

Resuming E Clocking



The E clock will resume normal operation at the end of the ½ cycle during which MR assertion meets the tpcs setup time. The tpcs setup time is referenced to transitions of E were it not stretched. If tpcs setup time is not met, E will fall at the second possible transition time after MR is asserted. There is no direct means of determining when the tpcs references occur, unless the synchronizing circuit of Figure 14 is used.



MOTOROLA Semiconductor Products Inc.

RAM ENABLE (RE - MC6802+ MC6802NS ONLY)

A TTL-compatible RAM enable input controls the on-chip RAM of the MC6802. When placed in the high state, the on-chip memory is enabled to respond to the MPU controls. In the low state, RAM is disabled. This pin may also be utilized to disable reading and writing the on-chip RAM during a power-down situation. RAM Enable must be low three cycles before VCC goes below 4.75 V during power-down. RAM enable must be tied low on the MC6808. RE should be tied to the correct high or low state if not used.

EXTAL AND XTAL

These inputs are used for the internal oscillator that may be crystal controlled. These connections are for a parallel resonant fundamental crystal (see Figure 12). (AT-cut.) A divide-by-four circuit has been added so a 4 MHz crystal may be used in lieu of a 1 MHz crystal for a more cost-effective system. An example of the crystal circuit layout is shown in Figure 13. Pin 39 may be driven externally by a TTL input signal four times the required E clock frequency. Pin 38 is to be grounded.

An RC network is not directly usable as a frequency source on pins 38 and 39. An RC network type TTL or CMOS oscillator will work well as long as the TTL or CMOS output drives the on-chip oscillator.

LC networks are not recommended to be used in place of the crystal.

If an external clock is used, it may not be halted for more than $tpW_{\phi L}$. The MC6802, MC6808 and MC6802NS are dynamic parts except for the internal RAM, and require the external clock to retain information.

MEMORY READY (MR)

MR is a TTL-compatible input signal controlling the stretching of E. Use of MR requires synchronization with the 4xf_O signal, as shown in Figure 14. When MR is high, E will be in normal operation. When MR is low, E will be stretched integral numbers of half periods, thus allowing interface to slow memories. Memory Ready timing is shown in Figure 15.

MR should be tied high (connected directly to V_{CC}) if not used. This is necessary to ensure proper operation of the part. A maximum stretch is $t_{\rm CVC}$.

ENABLE (E)

This pin supplies the clock for the MPU and the rest of the system. This is a single-phase, TTL-compatible clock. This clock may be conditioned by a memory read signal. This is equivalent to $\phi 2$ on the MC6800. This output is capable of driving one standard TTL load and 130 pF.

V_{CC} STANDBY (MC6802 ONLY)

This pin supplies the dc voltage to the first 32 bytes of RAM as well as the RAM Enable (RE) control logic. Thus, retention of data in this portion of the RAM on a power-up, power-down, or standby condition is guaranteed. Maximum current drain at VSB maximum is ISBB. For the MC6802NS this pin must be connected to VCC.

MPU INSTRUCTION SET

The instruction set has 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions (Tables 2 through 6). The instruction set is the same as that for the MC6800.

MPU ADDRESSING MODES

There are seven address modes that can be used by a programmer, with the addressing mode a function of both the type of instruction and the coding within the instruction. A summary of the addressing modes for a particular instruction can be found in Table 7 along with the associated instruction execution time that is given in machine cycles. With a bus frequency of 1 MHz, these times would be microseconds.

ACCUMULATOR (ACCX) ADDRESSING

In accumulator only addressing, either accumulator A or accumulator B is specified. These are one-byte instructions.

IMMEDIATE ADDRESSING

In immediate addressing, the operand is contained in the second byte of the instruction except LDS and LDX which have the operand in the second and third bytes of the instruction. The MPU addresses this location when it fetches the immediate instruction for execution. These are two- or three-byte instructions.

DIRECT ADDRESSING

In direct addressing, the address of the operand is contained in the second byte of the instruction. Direct addressing allows the user to directly address the lowest 256 bytes in the machine, i.e., locations zero through 255. Enhanced execution times are achieved by storing data in these locations. In most configurations, it should be a random-access memory. These are two-byte instructions.

EXTENDED ADDRESSING

In extended addressing, the address contained in the second byte of the instruction is used as the higher eight bits of the address of the operand. The third byte of the instruction is used as the lower eight bits of the address for the operand. This is an absolute address in memory. These are three-byte instructions.

INDEXED ADDRESSING

In indexed addressing, the address contained in the second byte of the instruction is added to the index register's lowest eight bits in the MPU. The carry is then added to the higher order eight bits of the index register. This result is then used to address memory. The modified address is held in a temporary address register so there is no change to the index register. These are two-byte instructions.



MC6802 • MC6808 • MC6802NS

IMPLIED ADDRESSING

In the implied addressing mode, the instruction gives the address (i.e., stack pointer, index register, etc.). These are one-byte instructions.

RELATIVE ADDRESSING

In relative addressing, the address contained in the second

byte of the instruction is added to the program counter's lowest eight bits plus two. The carry or borrow is then added to the high eight bits. This allows the user to address data within a range of -125 to +129 bytes of the present instruction. These are two-byte instructions.

TABLE 2 — MICROPROCESSOR INSTRUCTION SET — ALPHABETIC SEQUENCE

ABA	Add Accumulators	CLR	Clear	PUL	Pull Data
ADC ADD AND ASL ASR	Add with Carry Add Logical And Arithmetic Shift Left Arithmetic Shift Right	CLV CMP COM CPX	Clear Overflow Compare Complement Compare Index Register	ROL ROR RTI RTS	Rotate Left Rotate Right Return from Interrupt Return from Subroutine
BCC BCS BEQ BGE BGT BHI BIT BLE	Branch if Carry Clear Branch if Carry Set Branch if Equal to Zero Branch if Greater or Equal Zero Branch if Greater than Zero Branch if Higher Bit Test Branch if Less or Equal	DAA DEC DES DEX EOR INC INS	Decimal Adjust Decrement Decrement Stack Pointer Decrement Index Register Exclusive OR Increment Increment Stack Pointer Increment Index Register	SBA SBC SEC SEI SEV STA STS STX SUB	Subtract Accumulators Subtract with Carry Set Carry Set Interrupt Mask Set Overflow Store Accumulator Store Stack Register Store Index Register Subtract
BLS BLT BMI	Branch if Lower or Same Branch if Less than Zero Branch if Minus	JMP JSR	Jump Jump to Subroutine	SWI TAB	Software Interrupt Transfer Accumulators
BNE BPL BRA BSR BVC	Branch if Not Equal to Zero Branch if Plus Branch Always Branch to Subroutine Branch if Overflow Clear	LDA LDS LDX LSR	Load Accumulator Load Stack Pointer Load Index Register Logical Shift Right	TAP TBA TPA TST TSX	Transfer Accumulators to Condition Code Reg. Transfer Accumulators Transfer Condition Code Reg. to Accumulator Test
BVS	Branch if Overflow Set	NEG NOP	Negate No Operation	TXS	Transfer Stack Pointer to Index Register Transfer Index Register to Stack Pointer
CBA CLC	Compare Accumulators Clear Carry	ORA	Inclusive OR Accumulator	WAI	Wait for Interrupt
CLI	Clear Interrupt Mask	PSH	Push Data		



TABLE 3 — ACCUMULATOR AND MEMORY INSTRUCTIONS

		ADDRESSING MODES												BOOLEAN/ARITHMETIC OPERATION					. CO	DE	ĸĒ	
		11	IMMED		D	REC	Т	- 11	NDE	(E	XTN	D	IM	PLIE	D	(All register labels	5	4			1
OPERATIONS	MNEMONIC	OP	~	=	OP	_	=	OP	-	=	OP	~	=	OP	~	=	refer to contents)	н	1	N	Z١	٧Ţ
Add	ADDA	38	2	2	98	3	2	ΑВ	5	2	вв	4	3				A+M -A	1:	•	!	:	:
	ADDB	CB	2	2	DB	3	2	EB	5	2	FB	4	3				B + M - B	1	•	1 1		1
Add Acmitrs	ABA													18	2	1	A + B - A	:	•	1		!
Add with Carry	ADCA	89	2	2	99	3	2	A9	5	2	89	4	3				A + M + C - A	1	•	1		:
	ADCB	C9	2	2	D9	3	2	E9	5	2	F9	4	3				B + M + C · B	:	•			:
And	ANDA	84	2	2	94	3	2	A4	5	2	B4	4	3				A·M·A	•	•			R
0 . T	ANDB	C4	2	2	D4	3	2	E4	5	2	F4	4	3				B·M·B		•	:		R
Bit Test	BITA BITB	85 C5	2	2	95 D5	3	2	A5 E5	5 5	2	B5 F5	4	3				A·M B·M		•	1		R
Clear	CLR	"	2	۷	03	3	۷	6F	7	2	7 F	6	3				00 - M			R		R
Cicai	CLRA							١,,	,	-	''	U	,	4F	2	1	00 - A		•	R		R
	CLRB													5F	2	1	00 · B		•	R		R
Compare	CMPA	81	2	2	91	3	2	Αī	5	2	81	4	3		-		A M			1		:
	CMPB	C1	2	2	01	3	2	Ε1	5	2	F1	4	3				в м	•	•	:	i	:
Compare Acmitrs	CBA	1												11	2	1	A · B	•	•	:	:	:
Complement, 1's	COM							63	7	2	73	6	3				M - M	•	•	1	:	R
	COMA													43	2	1	Ā · A	•	•	:	1	R
	COMB										1			53	2	1	B ⋅B	•	•	:		R
Complement, 2's	NEG							60	7	2	70	6	3				00 M - M	•	•	:		<u> </u>
(Negate)	NEGA													40	2	1	00 A · A	•	•	1		D
	NEGB	1												50	2	1	00 B · B	•	•			DK
Decimal Adjust, A	DAA	1												19	2	1	Converts Binary Add. of BCD Characters	•	•	:	1	: (
		1						٠.			١,,	•					into BCD Format		١.		ا	ᅰ
Decrement	DEC							6A	7	2	7A	б	3	۱,,	-		M 1 - M	•	•	:		
	DECA	1									1			4A	2	1	A 1 · A	•	•	:		9
F 0.0	DECB		2	2	00	,	,	1 40	c	,	 po		,	5A	2	1	B 1 -B		•	:		4) R
Exclusive OR	EORA EORB	88 C8	2	2	98 D8	3	2	A8 E8	5 5	2	B8 F8	4	3				A⊕M · A B⊕M · B			:		R
Increment	INC	1 60	2	2	00	3	2	60	7	2	70	6	3				M + 1 - M			!		3
merement	INCA							1 00	′	2	/ "	0	3	4 C	2	1	A+1 -A					3
	INCB	l						l						5 C	2	i	B+1 -B		•			3
Load Acmitr	LDAA	86	2	2	96	3	2	A6	5	2	В6	. 4	3	"	-		M · A			:		R
Cond Activity	LDAB	C6	2	2	D6	3	2	E6	5	2	F6	4	3				M ·B			1	1.1	R
Or, Inclusive	ORAA	8A	2	2	9A	3	2	AA	5	2	ВА	4	3	ĺ			A+M · A			:		R
O1, morasive	ORAB	CA	2	2	DA	3	2	EA	5	2	FA	4	3				B + M · B			li		R
Push Data	PSHA		_			-								36	4	1	A · MSP, SP 1 · SP				•	•
	PSHB	1												37	4	1	B · MSP, SP 1 · SP			•	•	•
Pull Data	PULA	1												32	4	1	SP + 1 · SP, MSP · A				•	•
	PULB													33	4	1	SP + 1 · SP, MSP · B	•	•	•	•	•
Rotate Left	ROL							69	7	2	79	6	3	1			M) [•	•	!	1:(®
	ROLA	1			1			1			1			49	2	1		•		1		➂
	ROLB										ĺ			59	2	1	B C 67 - 60	•	•	1:		⊚
Rotate Right	ROR							66	7	2	76	6	3				M	•	•	1:		ⓒ
	RORA	1												46	2	1	A C b7 - b0	•	•	1		⊚
	RORB									_	١		_	56	2	1	1 6 2	•	•	1:		9
Shift Left, Arithmetic	ASL	1			l			68	7	2	78	6	3		_		M	•	•	1:		9
	ASLA	1			1									48	2	1	A C b7 b0	•	•	!		<u></u>
	ASLB	1						١						58	2	1	1 0 /	•	•	1:		<u></u>
Shift Right, Arithmetic	ASR							6/	7	2	77	6	3		2		*	•	•	1:		9
	ASRA	1									1			47	2	1	A 67 60 C	•	•	:		9
Chile Chale Land	ASRB							64	,	2	74	,	3	57	2	1	1 0 (:		9
Shift Right, Logic	LSR				1			64	7	2	/"	6	3	44	2	1	M		1 -	R		9
	LSRA	1												54	2	1	A 0 - 1 - 1 - C B b7 b0 C			1		(G)
Store Acmitr	LSRB STAA	1			97	4	2	A7	6	2	B7	5	3	34	2	'	A - M		1			R
Store Actual	STAB	1			07	4	2	E7	6	2	1	5	3	1			B·M			:	1 1	R
Subtract	SUBA	80	2	2	90	3	2	AO	5	2		4	3				A M · A			1		1
Outract	SUBB	CO		2	00		2	EO	5	2		4	3				S M ·B					
Subtract Acmitrs.	SBA	"	•	٠	"	٠	-	-	٠	-			J	10	2	1	A B · A			1 '	1 1	:
Subtr. with Carry	SBCA	82	2	2	92	3	2	A2	5	2	В2	4	3		-		A · M - C · A			1	i : I	
	SBCB	C2			02		2			2			3				B - M - C - B			li		
Transfer Acmitrs	TAB	1	-	-	-	-		1	-		1			16	2	1	A ·B			1:	;	R
	TBA	1												17	2	1						R
Test, Zero or Minus	TST	1						60	7	2	70	6	3	1			M - 00			1		R
	TSTA										1			4 D	2	1	A contract of the contract of	•	•			R
	TSTB	1			1			1			I			5 D		1						R

LEGEND:

- OP Operation Code (Hexadecimal);
- Number of MPU Cycles;
- Number of Program Bytes:
- Arithmetic Plus;
- Arithmetic Minus;
- Boolean AND;
- MSP Contents of memory location pointed to be Stack Pointer;
- Boolean Inclusive OR;
- Boolean Exclusive OR;
- Complement of M;
- Transfer Into: 0
- Bit = Zero; 00 Byte = Zero;
- Note Accumulator addressing mode instructions are included in the column for IMPLIED addressing

CONDITION CODE SYMBOLS:

- Half-carry from bit 3;
- Interrupt mask Negative (sign bit)
- Zero (byte)
- Overflow, 2's complement
- Carry from bit 7
- Reset Always
- Set Always
- Test and set if true, cleared otherwise

H I N Z V C



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TABLE 4 - INDEX REGISTER AND STACK MANIPULATION INSTRUCTIONS

COND. CODE REG. IMMED DIRECT INDEX EXTND IMPLIED 5 4 3 2 1 0 OP ~ = BOOLEAN/ARITHMETIC OPERATION POINTER OPERATIONS MNEMONIC | OP | ~| = OP ~ = OP ~ = OP ~ = HINZVC 3 3 9C 4 6 2 • • 7 : 8 • 2 AC BC 5 $X_{H} - M, X_{L} - (M + 1)$ Compare Index Reg 09 $X = 1 \rightarrow X$ Decrement Index Reg DEX 34 SP - 1 - SP Decrement Stack Pntr DES 4 1 Increment Index Reg INX 80 4 $X + 1 \rightarrow X$ SP + 1 → SP 4 Increment Stack Pntr INS 31 1 9 : R 9 : R 9 : R 9 : R DE EE FE 3 $M \rightarrow X_H$, $(M + 1) \rightarrow X_L$ Load Index Reg LDX CE 3 3 4 2 6 2 5 M - SPH, (M + 1) - SPL Load Stack Pntr LDS 8E 3 9E 4 ΑE 6 2 ВE 5 XH -M, XL -(M+1) DF FF Store Index Reg STX 5 2 EF 7 2 6 3 9F 5 2 7 2 ВF 6 SPH -- M, SPL -- (M + 1) Store Stack Pntr STS AF 3 Indx Reg → Stack Pntr TXS 35 4 X · 1 · SP 30 SP + 1 - X Stack Pntr • Indx Reg TSX

TABLE 5 — JUMP AND BRANCH INSTRUCTIONS

COND. CODE REG. E A 2 2 1 0

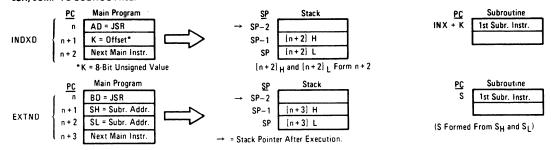
																0310	D. C	UDL		
		RE	LAT	VE	11	NDE	x	E	XTN	D	IM	PLIE	D		5	4	3	2	1	0
OPERATIONS	MNEMONIC	OP	~	#	OP	~	#	OP	~	#	OP	~	#	BRANCH TEST	Н	1	N	Z	٧	C
Branch Always	BRA	20	4	2										None	•	•	•	•	•	•
Branch If Carry Clear	BCC	24	4	2										C = 0	•	•	•	•	•	•
Branch If Carry Set	B CS	25	4	2			1							C = 1	•	•	•	•	•	•
Branch If = Zero	BEQ	27	4	2										Z = 1	•	•	•	•	•	•
Branch If ≥ Zero	BGE	2 C	4	2										N ⊕ V = 0	•	•	•	•	•	•
Branch If > Zero	BGT	2E	4	2									ļ	$Z + (N \oplus V) = 0$	•	•	•	•	•	•
Branch If Higher	ВНІ	22	4	2										C + Z = 0	•	•	•	•	•	•
Branch If ≤ Zero	BLE	2F	4	2			ŀ			İ				Z + (N 🕀 V) = 1	•	•	•	•	•	•
Branch If Lower Or Same	BLS	23	4	2										C + Z = 1	•	•	•	•	•	•
Branch If < Zero	BLT	2D	4	2				İ						N ⊕ V = 1	•	•	•	•	•	•
Branch If Minus	BMI	2B	4	2										N = 1	•	•	•	•	•	•
Branch If Not Equal Zero	BNE	26	4	2				ĺ						Z = 0	•	•	•	•	•	•
Branch If Overflow Clear	BVC	28	4	2				ĺ						V = 0	•	•	•	•	•	•
Branch If Overflow Set	BVS	29	4	2										V = 1	•	•	•	•	•	•
Branch If Plus	BPL	2A	4	2				1						N = 0	•	•	•	•	•	•
Branch To Subroutine	BSR	8D	8	2											•	•	•	•	•	•
Jump	JMP		i		6E	4	2	7E	3	3				See Special Operations	•	•	•	•	•	•
Jump To Subroutine	JSR				AD	8	2	BD	9	3		1	ł) (Figure 16)	•	•	•	•	•	•
No Operation	NOP	İ		1	l			1		ŀ	01	2	1	Advances Prog. Cntr. Only	•	•	•		•	•
Return From Interrupt	RTI										3B	10	1		-		- (10) -		
Return From Subroutine	RTS										39	5	1		•	•	•	•	•	•
Software Interrupt	SWI										3F	12	1	See Special Operations	•	•	•	•	•	•
Wait for Interrupt	WAI	1						1			3 E	9	1	(Figure 16)	•	(1)	•	•	•	•



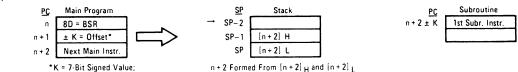
FIGURE 16 - SPECIAL OPERATIONS

SPECIAL OPERATIONS

JSR, JUMP TO SUBROUTINE:



BSR, BRANCH TO SUBROUTINE:



JMP, JUMP:

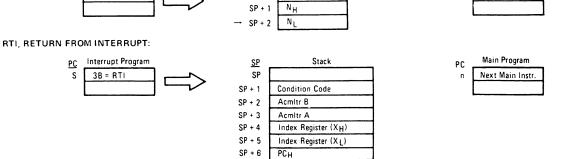


SP

RTS, RETURN FROM SUBROUTINE:

Subroutine

39 = RTS



Stack

TABLE 6 - CONDITION CODE REGISTER MANIPULATION INSTRUCTIONS

PCL

 \rightarrow SP + 7

COND. CODE REG.

<u>PC</u>

Main Program

Next Main Instr.

		IN	PLIE	D		5	4	3	2	1	0
OPERATIONS	MNEMONIC	OP	~	=	BOOLEAN OPERATION	Н	1	N	z	v	С
Clear Carry	CLC	00	2	1	0 C	•	•	•	•	•	R
Clear Interrupt Mask	CLI	0E	2	1	0 1	•	R	•	•	•	•
Clear Overflow	CLV	0A	2	1	0 - V	•	•	•	•	R	•
Set Carry	SEC	00	2	1	1 → C	•	•	•	•	•	S
Set Interrupt Mask	SEI	0F	2	1	1 1	•	S	•	•	•	•
Set Overflow	SEV	ОВ	2	1	1 → V	•	•	•	•	S	•
Acmltr A → CCR	TAP	06	2	1	A → CCR	·		(i	2)—		
CCR → Acmitr A	TPA	07	2	1	CCR -+ A	•	•	•	•	•	

CONDITION CODE REGISTER NOTES: (Bit set if test is true and cleared otherwise)

1	(Bit V)	Test: Result = 10000000?	7	(Bit N)	Test: Sign bit of most significant (MS) byte = 1?
2	(Bit C)	Test: Result # 00000000?	8	(Bit V)	Test: 2's complement overflow from subtraction of MS bytes?
3	(Bit C)	Test: Decimal value of most significant BCD Character greater than nine?	9	(Bit N)	Test: Result less than zero? (Bit 15 = 1)
		(Not cleared if previously set.)	10	(AII)	Load Condition Code Register from Stack. (See Special Operations)
4	(Bit V)	Test: Operand = 10000000 prior to execution?	11	(Bit I)	Set when interrupt occurs. If previously set, a Non-Maskable
5	(Bit V)	Test: Operand = 01111111 prior to execution?			Interrupt is required to exit the wait state.
6	(Bit V)	Test: Set equal to result of N⊕C after shift has occurred.	12	(AII)	Set according to the contents of Accumulator A.



TABLE 7 — INSTRUCTION ADDRESSING MODES AND ASSOCIATED EXECUTION TIMES (Times in Machine Cycle)

	(Dual Operand)	ACCX	Immediate	Direct	Extended	Indexed	Implied	Relative		(Dual Operand)	ACCX	Immediate	Direct	Extended	Indexed	Implied
ABA ADC	×	•	2	3	• 4	5	2	•	INC INS		2 •	•	•	6 •	7 •	4
ADD AND	X	•	2	3 3	4	5	•	•	INX JMP		•	•	•	• 3	4	4
ASL	×	2	•	3	6	5 7	•	•	JSR		•	•	•	9	8	:
ASR		2	•	•	6	7	•	•	LDA	×	•	2	3	4	5	•
BCC		•	•	•	•	•	•	4	LDS		•	3	4	5	6	•
BCS		•	•	•	•	•	•	4	LDX		•	3	4	5	6	•
BEA BGE		•	•	•	•	•	•	4	LSR NEG		2	•	•	6 6	7 7	•
BGT		•	•	•	•	•	•	4	NOP		•	•	•	•	•	2
BHI		•	•	•	•	•	•	4	ORA	×	•	2	3	4	5	•
BIT	x	•	2	3	4	5	•	•	PSH		•	•	•	•	•	4
BLE		•	•	•	•	•	•	4	PUL		•	•	•	•	•	4
BLS		•	•	٠	•	•	•	4	ROL		2	•	•	6 6	7 7	•
BLT BMI		•	•	•	•	•	•	4	ROR RTI		2	•	•	•	•	10
BNE		:	•	•	:	•	•	4	RTS		•	•	•	•	•	5
BPL		•	•	•	•	•	•	4	SBA		•	•	•	•	•	2
BRA		•	•		•	•	•	4	SBC	X	•	2	3	4	5	•
BSR		•	•	•	•	•	•	8	SEC		•	•	•	•	•	2
BVC		•	•	•	•	•	•	4	SEI		•	•	•	•	•	2
BVS		•	•	•	•	•	•	4	SEV STA	v	•	•	4	5	6	2
CBA CLC		•	•	•	•	•	2	•	STS	X	•	•	5	6	7	•
CLI		:	:	•	•	:	2		STX		•	•	5	6	7	•
CLR		2	•	•	6	7	•	•	SUB	x	•	2	3	4	5	•
CLV		•	•	•	•	•	2	•	SWI		•	•	•	•	•	12
CMP	X	•	2	3	4	5	•	•	TAB		•	•	•	•	•	2
COM		2	•	•	6	7	•	•	TAP		•	•	•	•	•	2 2 2
CPX		•	3	4	5	6	•	•	TBA		•	•	•	•	•	2
DAA DEC		2	•	•	6	• 7	2	•	TPA TST		2	•	•	6	• 7	•
DES		•	•	•	•	•	4	•	TSX		•	•	•	•	•	4
DEX		•	•	•	•	•	4	•	TSX		•	•	•	•	•	4
EOR	×	•	2	3	4	5	•	•	WAI		•	•	•	•	•	9

NOTE: Interrupt time is 12 cycles from the end of the instruction being executed, except following a WAI instruction. Then it is 4 cycles.

SUMMARY OF CYCLE-BY-CYCLE OPERATION

Table 8 provides a detailed description of the information present on the address bus, data bus, valid memory address line (VMA), and the read/write line (R/ \overline{W}) during each cycle for each instruction.

This information is useful in comparing actual with expected results during debug of both software and hardware

as the control program is executed. The information is categorized in groups according to addressing modes and number of cycles per instruction. (In general, instructions with the same addressing mode and number of cycles execute in the same manner; exceptions are indicated in the table.)

TABLE 8 - OPERATIONS SUMMARY

Address Mode	1	Cycle	VMA		R/W	
and Instructions	Cycles	#	Line	Address Bus	Line	Data Bus
IMMEDIATE						
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA AND ORA	2	2	1	Op Code Address + 1	1	Operand Data
BIT SBC	1					
CMP SUB	 					
CPX LDS		1	1	Op Code Address	1	Op Code
LDX	3	2	1	Op Code Address + 1	1	Operand Data (High Order Byte)
0.0507	J	3	1 1	Op Code Address + 2	1	Operand Data (Low Order Byte)
DIRECT	т	r	г		1	
ADC EOR ADD LDA		1	1	Op Code Address	1	Op Code
AND ORA	3	2	1	Op Code Address + 1	1	Address of Operand
BIT SBC CMP SUB		3	1	Address of Operand	1	Operand Data
CPX LDS		1	1	Op Code Address	1	Op Code
LDX	4	2	1	Op Code Address + 1	1	Address of Operand
		3	1	Address of Operand	1	Operand Data (High Order Byte)
		4	1	Operand Address + 1	1	Operand Data (Low Order Byte)
STA		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Destination Address
		3	0	Destination Address	1	Irrelevant Data (Note 1)
		4	1	Destination Address	0	Data from Accumulator
STS		1	1	Op Code Address	1	Op Code
STX		2	1	Op Code Address + 1	1	Address of Operand
	5	3	0	Address of Operand	1	Irrelevant Data (Note 1)
		4	1	Address of Operand	0	Register Data (High Order Byte)
		5	1	Address of Operand + 1	0	Register Data (Low Order Byte)
INDEXED						
JMP		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA AND ORA		2	1	Op Code Address + 1	1	Offset
BIT SBC	5	3	0	Index Register	1	Irrelevant Data (Note 1)
CMP SUB		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Operand Data
CPX		1	1	Op Code Address	1	Op Code
LDS		2	1	Op Code Address + 1	1	Offset
	6	3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Operand Data (High Order Byte)
	1	6	1	Index Register Plus Offset + 1	1	Operand Data (Low Order Byte)



TABLE 8 — OPERATIONS SUMMARY (CONTINUED)

Address Mode and Instructions	Cycles	Cycle #	Line	Address Bus	R/W Line	Data Bus
INDEXED (Continued)						
STA		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
	6	3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1 1	Irrelevant Data (Note 1)
		5	0	Index Register Plus Offset	1 1	Irrelevant Data (Note 1)
		6	1	Index Register Plus Offset	0	Operand Data
ASL LSR		1	1	Op Code Address	1	Op Code
ASR NEG CLR ROL		2	1	Op Code Address + 1	1 1	Offset
COM ROR	7	3	0	Index Register	1 1	Irrelevant Data (Note 1)
DEC TST INC		4	0	Index Register Plus Offset (w/o Carry)	1 1	Irrelevant Data (Note 1)
		5	1	Index Register Plus Offset	1	Current Operand Data
		6	0	Index Register Plus Offset	1 1	Irrelevant Data (Note 1)
		7	1/0 (Note	Index Register Plus Offset	0	New Operand Data (Note 3)
			3)			
STS		1	1	Op Code Address	1	Op Code
STX		2	1	Op Code Address + 1	1	Offset
	7	3	0	Index Register	1	Irrelevant Data (Note 1)
		4	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
		5	0	Index Register Plus Offset	1	Irrelevant Data (Note 1)
		6	1	Index Register Plus Offset	0	Operand Data (High Order Byte)
		7	1	Index Register Plus Offset + 1	0	Operand Data (Low Order Byte)
JSR		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Offset
		3	0	Index Register	1	Irrelevant Data (Note 1)
	8	4	1	Stack Pointer	0	Return Address (Low Order Byte)
	•	5	1	Stack Pointer — 1	0	Return Address (High Order Byte)
		6	0	Stack Pointer — 2	1	Irrelevant Data (Note 1)
		7	0	Index Register	1	Irrelevant Data (Note 1)
	ļ	8	0	Index Register Plus Offset (w/o Carry)	1	Irrelevant Data (Note 1)
EXTENDED						
JMP		1	1	Op Code Address	1	Op Code
	3	2	1	Op Code Address + 1	1	Jump Address (High Order Byte)
	1	3	1	Op Code Address + 2	1	Jump Address (Low Order Byte)
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA		2	1	Op Code Address + 1	1	Address of Operand (High Order Byt
AND ORA BIT SBC	4	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte
CMP SUB		4	1	Address of Operand	1	Operand Data
CPX		1	1	Op Code Address	1	Op Code
LDS	1	2	1	Op Code Address + 1	1	Address of Operand (High Order Byt
LDX	5	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byt
	1	4	1	Address of Operand	1	Operand Data (High Order Byte)
		5	1	Address of Operand + 1	1	Operand Data (Low Order Byte)
STA A	+	1	+ +	Op Code Address	1	Op Code
STA B		2		Op Code Address + 1	1	Destination Address (High Order Byt
	5	3	1	Op Code Address + 2	'1	Destination Address (Low Order Byt
	"	4	0	Operand Destination Address	;	Irrelevant Data (Note 1)
		5	1	Operand Destination Address Operand Destination Address	'	Data from Accumulator
ACL LCD		1	1	Op Code Address	1	Op Code
ASL LSR ASR NEG			'		l l	
CLR ROL		2		Op Code Address + 1	1	Address of Operand (High Order Byt
COM ROR DEC TST	6	3	1 1	Op Code Address + 2		Address of Operand (Low Order Byt
INC		4	1	Address of Operand	1 1	Current Operand Data
		5	0	Address of Operand	1	Irrelevant Data (Note 1)
		6	1/0 (Note 3)	Address of Operand	0	New Operand Data (Note 3)



TABLE 8 — OPERATIONS SUMMARY (CONTINUED)

Address Mode and Instructions	Cycles	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
EXTENDED (Continued)						
STS		1	1 1	Op Code Address	1	Op Code
STX		2	1	Op Code Address + 1	1	Address of Operand (High Order Byte)
	6	3	1	Op Code Address + 2	1	Address of Operand (Low Order Byte)
		4	0	Address of Operand	1	Irrelevant Data (Note 1)
		5	1	Address of Operand	0	Operand Data (High Order Byte)
		6	1	Address of Operand + 1	0	Operand Data (Low Order Byte)
JSR		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Address of Subroutine (High Order Byte)
		3	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)
		4	1	Subroutine Starting Address	1	Op Code of Next Instruction
	9	5	1	Stack Pointer	0	Return Address (Low Order Byte)
		6	1	Stack Pointer — 1	0	Return Address (High Order Byte)
		7	0	Stack Pointer — 2	1	Irrelevant Data (Note 1)
		8	0	Op Code Address + 2	1	Irrelevant Data (Note 1)
		9	1	Op Code Address + 2	1	Address of Subroutine (Low Order Byte)
INHERENT	•					
ABA DAA SEC		1	1	Op Code Address	1	Op Code
ASL DEC SEI	2	2	1	Op Code Address + 1	1	Op Code of Next Instruction
ASR INC SEV CBA LSR TAB						
CLC NEG TAP						
CLI NOP TBA CLR ROL TPA			1			
CLV ROR TST	ļ					
COM SBA		_	ļ <u>.</u>		 	0.00
DES DEX		1 _	1	Op Code Address	1	Op Code
INS	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
INX		3	0	Previous Register Contents	1	Irrelevant Data (Note 1)
	ļ	4	0	New Register Contents	1 1	Irrelevant Data (Note 1)
PSH		1	1	Op Code Address	1 1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
	1	3	1	Stack Pointer	0	Accumulator Data
	<u> </u>	4	0	Stack Pointer — 1	1	Accumulator Data
PUL		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1 1	Operand Data from Stack
TSX	1	1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	0	New Index Register	1	Irrelevant Data (Note 1)
TXS		1	1	Op Code Address	1	Op Code
	4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
	1	3	0	Index Register	1	Irrelevant Data
		4	0	New Stack Pointer	1	Irrelevant Data
RTS		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 2)
	5	3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Address of Next Instruction (High Order Byte)
		5	1	Stack Pointer + 2	1	Address of Next Instruction (Low Order Byte)



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TABLE 8 — OPERATIONS SUMMARY (CONCLUDED)

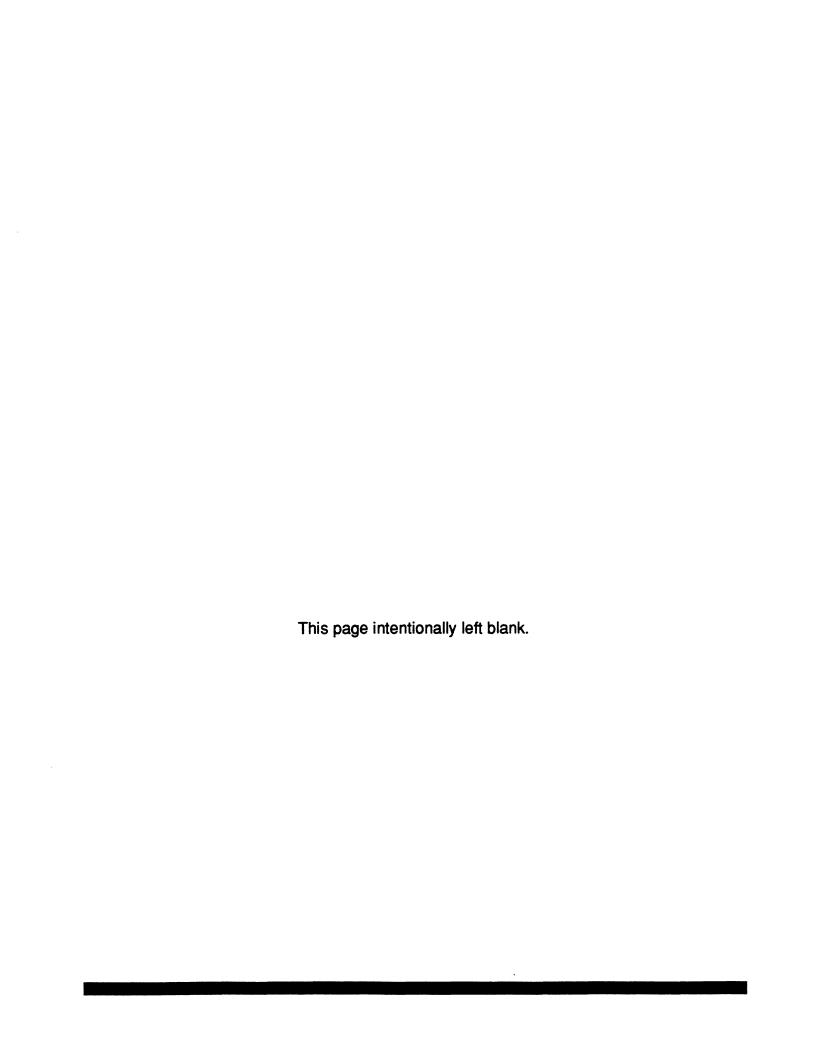
Address Mode and Instructions	Cycles	Cycle	VMA Line	Address Bus	R/W Line	Data Bus
INHERENT (Continued)	7 7 7 5 1 5 5	·				
WAI		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Op Code of Next Instruction
		3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer — 1	0	Return Address (High Order Byte)
	9	5	1	Stack Pointer — 2	0	Index Register (Low Order Byte)
		6	1	Stack Pointer — 3	0	Index Register (High Order Byte)
		7	1	Stack Pointer — 4	0	Contents of Accumulator A
		8	1	Stack Pointer — 5	0	Contents of Accumulator B
		9	1	Stack Pointer — 6	1	Contents of Cond. Code Register
RTI		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 2)
		3	0	Stack Pointer	1	Irrelevant Data (Note 1)
		4	1	Stack Pointer + 1	1	Contents of Cond. Code Register from Stack
	10	5	1	Stack Pointer + 2	1	Contents of Accumulator B from Stack
		6	1	Stack Pointer + 3	1	Contents of Accumulator A from Stack
		7	1	Stack Pointer + 4	1	Index Register from Stack (High Order Byte)
		8	1	Stack Pointer + 5	1	Index Register from Stack (Low Order Byte)
4		9	1	Stack Pointer + 6	1	Next Instruction Address from Stack (High Order Byte)
		10	1	Stack Pointer + 7	1	Next Instruction Address from Stack (Low Order Byte)
SWI		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Irrelevant Data (Note 1)
		3	1	Stack Pointer	0	Return Address (Low Order Byte)
		4	1	Stack Pointer — 1	0	Return Address (High Order Byte)
		5	1	Stack Pointer — 2	0	Index Register (Low Order Byte)
	12	6	1	Stack Pointer — 3	0	Index Register (High Order Byte)
	'-	7	1	Stack Pointer — 4	0	Contents of Accumulator A
		8	1	Stack Pointer — 5	0	Contents of Accumulator B
		9	1	Stack Pointer — 6	0	Contents of Cond. Code Register
		10	0	Stack Pointer 7	1	Irrelevant Data (Note 1)
		11	1	Vector Address FFFA (Hex)	1	Address of Subroutine (High Order Byte)
		12	1	Vector Address FFFB (Hex)	1	Address of Subroutine (Low Order Byte)
RELATIVE		,	,			
BCC BHI BNE		1	1	Op Code Address	1	Op Code
BCS BLE BPL BEQ BLS BRA	4	2	1	Op Code Address + 1	1	Branch Offset
BGE BLT BVC		3	0	Op Code Address + 2	1	Irrelevant Data (Note 1)
BGT BMI BVS		4	0	Branch Address	1	Irrelevant Data (Note 1)
BSR		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Branch Offset
		3	0	Return Address of Main Program	1	Irrelevant Data (Note 1)
	8	4	1	Stack Pointer	0	Return Address (Low Order Byte)
		5	1	Stack Pointer — 1	0	Return Address (High Order Byte)
		6	0	Stack Pointer — 2	1	Irrelevant Data (Note 1)
		7	0	Return Address of Main Program	1	Irrelevant Data (Note 1)
		8	0	Subroutine Address (Note 4)	1	Irrelevant Data (Note 1)

NOTES:

- 1. If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high-impedance three-state condition. Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.
- 2. Data is ignored by the MPU.
- 3. For TST, VMA=0 and Operand data does not change.
- 4. MS Byte of Address Bus = MS Byte of Address of BSR instruction and LS Byte of Address Bus = LS Byte of Sub-Routine Address.

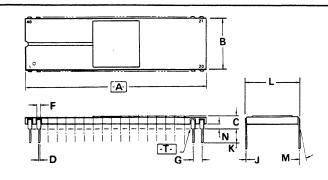


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PACKAGE DIMENSIONS



L SUFFIX **CERAMIC PACKAGE CASE 715-05**

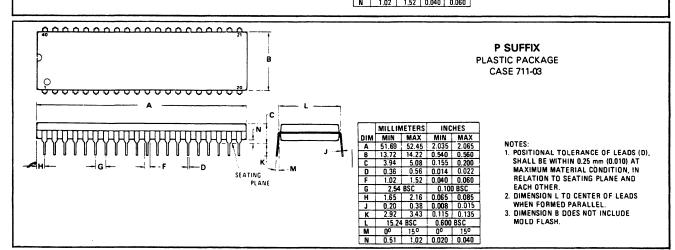
	MILLIM	ETERS	INCHES				
DIM	MIN	MAX	MIN	MAX			
Α	50.29	51.31	1.980	2.020			
В	14.63	15.49	0.576	0.610			
C	2.79	4.32	0.110	0.170			
D	0.38	0.53	0.015	0.021			
F	0.76	1.52	0.030	0.060			
G	2.54	BSC	0.100 BSC				
J	0.20	0.33	0.008	0.013			
K	2.54	4.57	0.100	0.180			
L	14.99	15.65	0.590	0.616			
М	_	100	-	100			
N	1.02	1 52	0.040	0.060			

NOTES

- 1. DIMENSION -A- IS DATUM.
- 2. POSITIONAL TOLERANCE FOR LEADS:

⊕ 0.25 (0.010) M T AM

- 3. T IS SEATING PLANE.
 4. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.



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